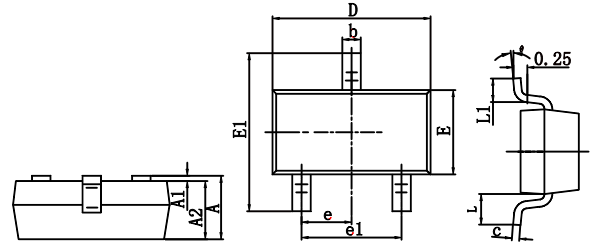


FEATURES

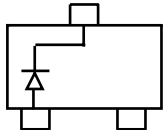
- Low Turn-on voltage
- Fast switching
- Ultra-small surface mount package
- Also available in lead free version

High temperature soldering : 260°C / 10 seconds at terminals
Pb free product at available : 99% Sn above meet RoHS environment substance directive request

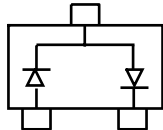
SOT-23 Unit:inch(mm)



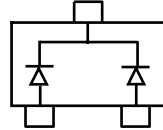
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	6°



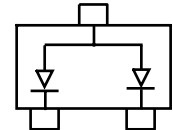
BAS70 Marking: 73



BAS70S Marking: 74



BAS70C Marking: 75



BAS70A Marking: 76

Maximum Rating $T_A=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Value	Unit
V_R	DC Voltage	70	V
I_F	Forward Continuous Current	70	mA
P_d	Power Dissipation	200	mW
T_J, T_{STG}	Junction Operating and Storage Temperature	-55 to +150	°C

Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min.	Max.	Unit
Reverse Breakdown Voltage	$V_{(BR)R}$	$I_R=10\mu\text{A}$	70	-	V
Reverse Leakage Current	I_R	$V_R=50\text{V}$	-	100	nA
Forward Voltage	V_F	$I_F=1\text{mA}$ $I_F=15\text{mA}$	-	410 1000	mV
Diode Capacitance	C_D	$V_R=0\text{V}, f=1\text{MHz}$	-	2	pF
Reverse Recovery Time	t_{rr}	$I_F=I_R=10\text{mA}, I_{rr}=0.1 \times I_R, R_L=100\Omega$	-	5	nS

DEVICE CHARACTERISTICS

BAS70/A/C/S

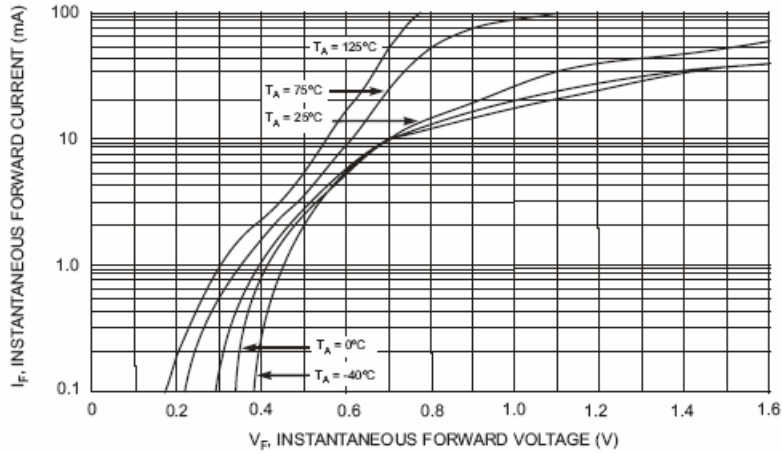


Fig. 1 Typical Forward Characteristics

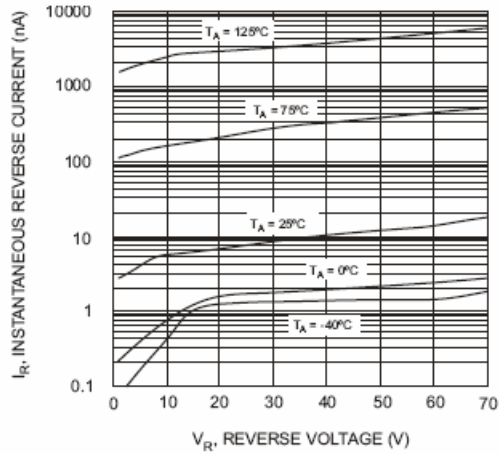


Fig. 2 Typical Reverse Characteristics

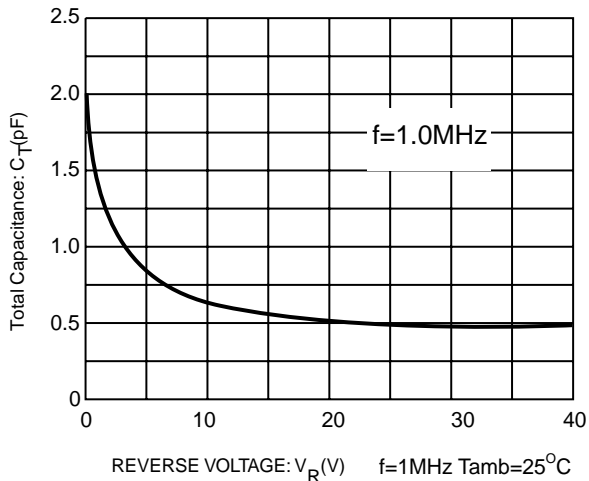


Fig.3 Typical Capacitance.

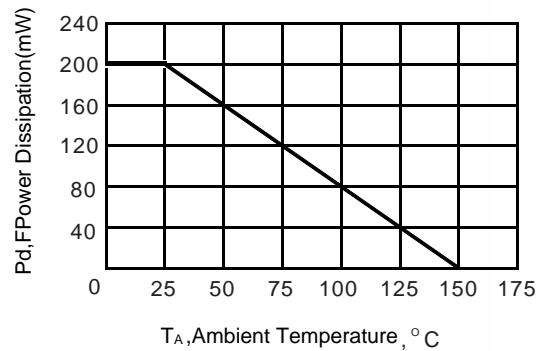


Fig.4-Power Derating Curve, Total Package

PACKAGE OUTLINE AND DIMENSIONS

BAS70/A/C/S

* SOLDERING FOOTPRINT

